

Features

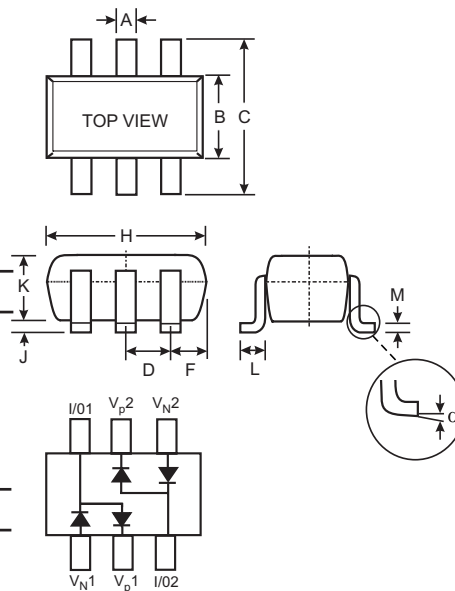
- ESD Protection >30kV (Human Body Model) (Note 1)
- Ultra-Small Surface Mount Package
- Protects 2 Data Lines
- Low Leakage <25nA
- Low Capacitance 3pF Typ.
- Protects USB 2.0 and USB 1.1
- **Lead Free by Design/RoHS Compliant (Note 4)**

IEC Compatibility (Note 1)

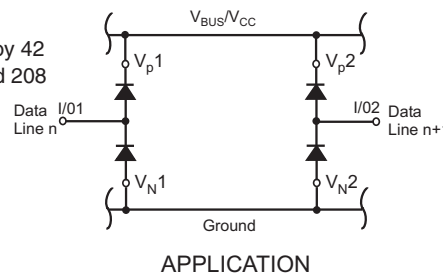
- 61000-4-2 (ESD) Air-30kV Contact-30kV
- 61000-4-4 (EFT) 40A, 5/50 ns
- 61000-4-5 (Surge) 8x20μs, 20 Amperes

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish — Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Orientation: See Diagram Below
- Marking: See Last Page
- Weight: 0.006 grams (approximate)



| SOT-363 | | |
|----------------------|--------------|------|
| Dim | Min | Max |
| A | 0.10 | 0.30 |
| B | 1.15 | 1.35 |
| C | 2.00 | 2.20 |
| D | 0.65 Nominal | |
| F | 0.30 | 0.40 |
| H | 1.80 | 2.20 |
| J | — | 0.10 |
| K | 0.90 | 1.00 |
| L | 0.25 | 0.40 |
| M | 0.10 | 0.25 |
| α | 0° | 8° |
| All Dimensions in mm | | |



APPLICATION

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|-----------------------------------------------------------------------------------------|---------------------------------|-------------|--------------------|
| Non-Repetitive Peak Reverse Voltage | V_{RM} | 100 | V |
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 80 | V |
| Forward Continuous Current (Note 2) | I_{FM} | 500 | mA |
| Repetitive Peak Forward Current @ $T_p = 5\mu\text{s}$, $f = 50\text{kHz}$ (Note 2) | I_{FRM} | 1000 | mA |
| Non-Repetitive Peak Forward Surge Current @ $t = 1.0\mu\text{s}$ @ $t = 1.0\text{s}$ | I_{FSM} | 20 2.0 | A |
| Clamping Voltage (Note 3) @ $I_{pp} = 20\text{A}$ 8x20μs Waveform | V_C | 16 | V |
| Power Dissipation (Note 2) | P_d | 200 | mW |
| Thermal Resistance, Junction to Ambient Air (Note 2) | $R_{\theta JA}$ | 625 | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range | T_j, T_{STG} | -65 to +150 | $^\circ\text{C}$ |

- Notes:
1. Tested with V_P connected to V_N to simulate appropriate V_{BUS}/V_{CC} decoupling to ground.
 2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 3. Referenced to V_P or V_N .
 4. No purposefully added lead.

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|----------------------------------------------|-------------|------|-----|-----------------------------|--------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------|
| Reverse Breakdown Voltage (Note 5) | $V_{(BR)R}$ | 80 | — | — | V | $I_R = 100\mu\text{A}$ |
| Forward Voltage | V_F | 0.62 | — | 0.72 0.93 1.0 1.25 | V | $I_F = 5.0\text{mA}$ $I_F = 20\text{mA}$ $I_F = 100\text{mA}$ $I_F = 150\text{mA}$ |
| Reverse Current (Note 5) | I_R | — | — | 100 50 30 25 | nA μA μA nA | $V_R = 70\text{V}$ $V_R = 75\text{V}, T_j = 150^\circ\text{C}$ $V_R = 25\text{V}, T_j = 150^\circ\text{C}$ $V_R = 20\text{V}$ |
| Capacitance, Between I/O Lines (I/O1 & I/O2) | C_{LL} | — | 2.5 | 4.0 | pF | $V_R = 0\text{V}, f = 1.0\text{MHz}$ |
| Capacitance Between I/O Line and Ground | C_{LG} | — | 3.3 | 5.3 | pF | $V_R = 0\text{V}, f = 1.0\text{MHz}$ |
| Reverse Recovery Time | t_{rr} | — | — | 4.0 | ns | $V_R = 6\text{V}, I_F = 5\text{mA}$ |

Notes: 5. Short duration test pulse used to minimize self-heating effect.

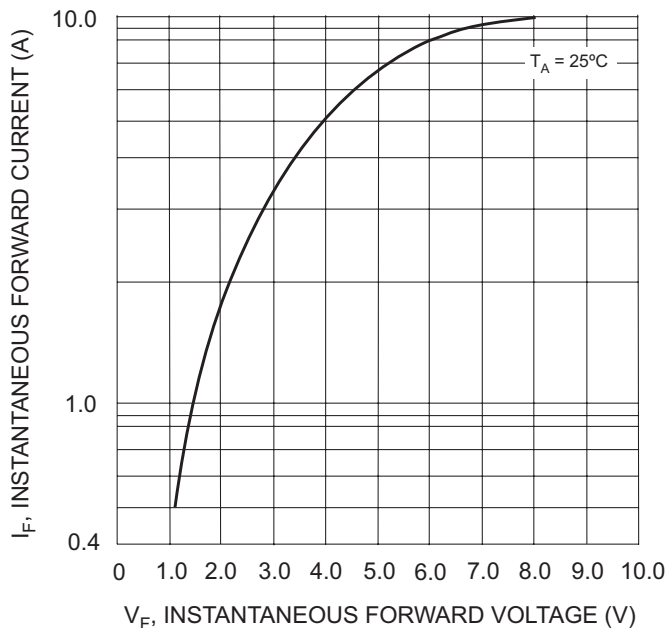


Fig. 1 Typical Forward Characteristics, High Current

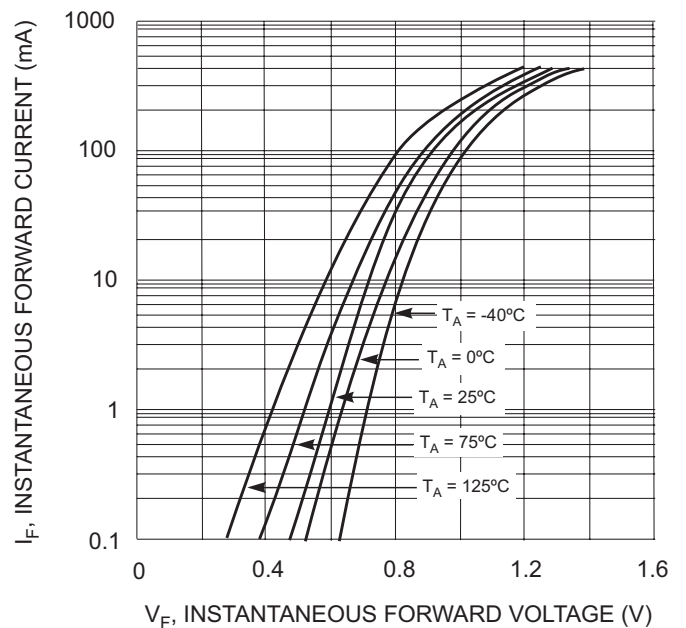


Fig. 2 Typical Forward Characteristics, Low Current

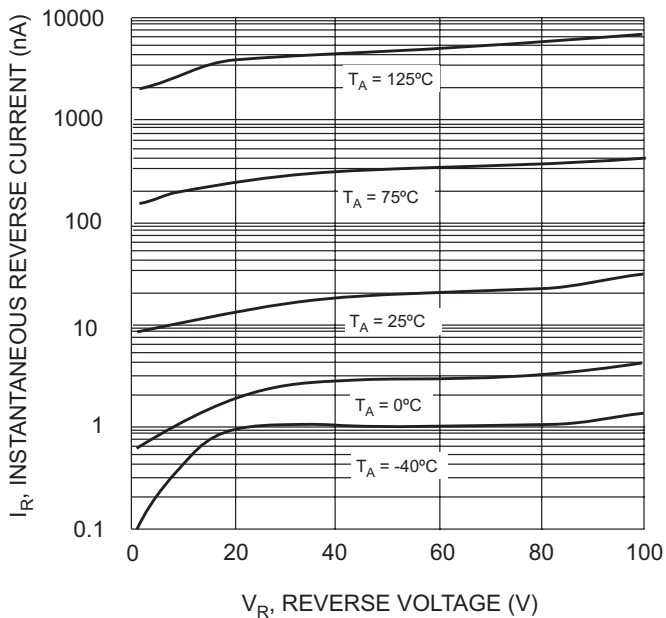


Fig. 3 Typical Reverse Characteristics

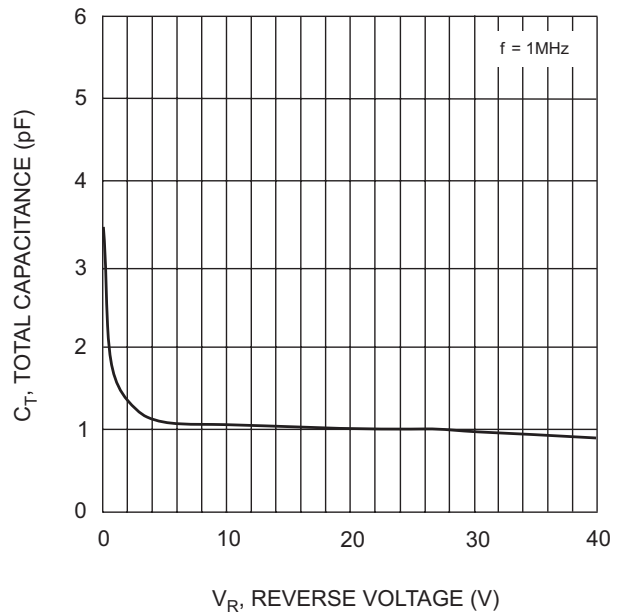


Fig. 4 Typical Capacitance vs. Reverse Voltage One Diode Element

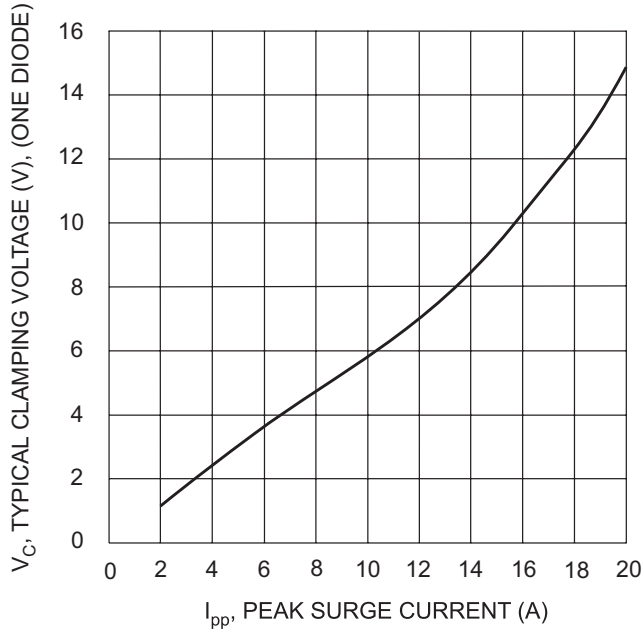


Fig. 5 61000-4-5 8x20 μ s Lightning Surge Response

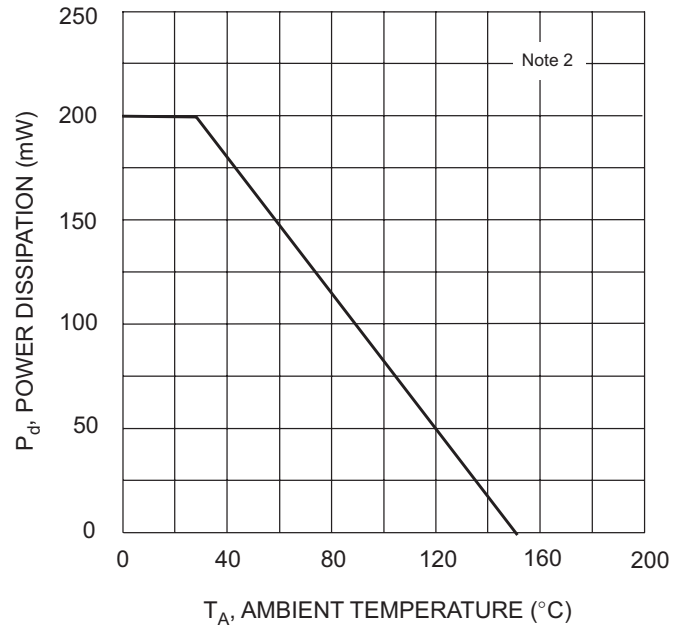
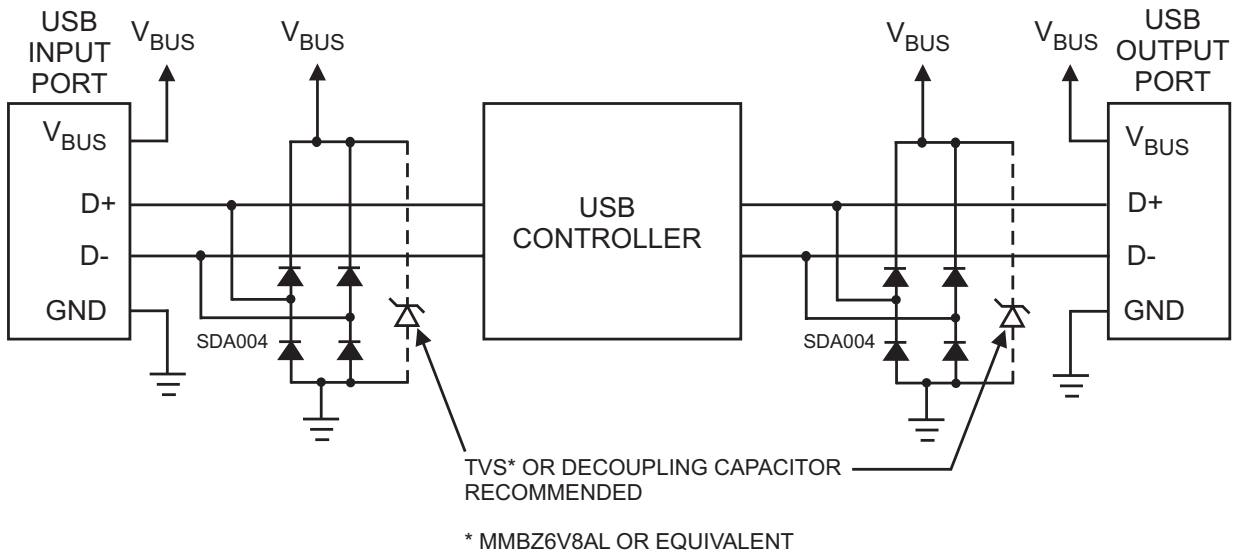


Fig. 6 Power Derating Curve, Total Package



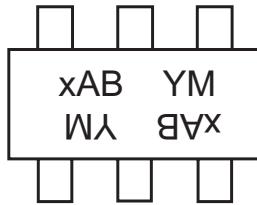
ESD PROTECTION - USB APPLICATION

Ordering Information (Note 6)

| Device | Packaging | Shipping |
|----------|-----------|------------------|
| SDA004-7 | SOT-363 | 3000/Tape & Reel |

Notes: 6. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



SOT-363

KAB or JAB = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: R = 2004
 M = Month ex: 9 = September

Date Code Key

| Year | 2004 | 2005 | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 |
|------|------|------|------|------|------|------|------|------|------|
| Code | R | S | T | U | V | W | X | Y | Z |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

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